Contribution ID: **9** Type: **Oral presentation**

Development of Interconnect Technologies for HEP Applications

Thursday 4 February 2010 08:30 (20 minutes)

HEP detectors are continually advancing towards higher segmentation of elements and higher complexity in assembly architectures. The task of interconnecting detector elements with readout electronics and with readout buses for such detectors poses new challenges and opportunities. We will address progress on several fronts: gold stud bonding, anisotropic conducting films, conductive epoxy stencils and flexible cable attachments. Some speculative concepts such as use of PDMS for single-die photolithography and as low-mass interposers will also be presented. Our work is aimed at generic R&D but focused towards detectors for the ILC and SuperLHC.

Primary author: TRIPATHI, Mani (Department of Physics-University of California (UCD)-Unknown)

Presenter: TRIPATHI, Mani (Department of Physics-University of California (UCD)-Unknown)

Session Classification: Development of specific components, for example low mass interposers

Track Classification: Development of specific components, for example low mass interposers